

# IGBT - Field Stop, Trench

## 650 V, 75 A

### Product Preview

## FGH75T65SHDTLN4

Using the novel field stop 3rd generation IGBT technology, FGH75T65SHDTLN4 offers the optimum performance for solar inverter, UPS, welder, telecom, ESS and PFC applications where low conduction loss and switching loss are essential.

#### Features

- Maximum Junction Temperature:  $T_J = 175^\circ\text{C}$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage:  $V_{CE(\text{Sat})} = 1.6\text{ V (Typ.) @ } I_C = 75\text{ A}$
- 100% of the Parts Tested for  $I_{LM}(1)$
- High Input Impedance
- Fast Switching
- Tight Parameter Distribution
- Pb Free and RoHS Compliant
- Not Recommended for Reflow and Full PKG Dipping

#### Typical Applications

- Solar Inverter      • UPS      • Welder
- Telecom      • ESS      • PFC

#### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit	
Collector-to-Emitter Voltage	$V_{CES}$	650	V	
Gate-to-Emitter Voltage Transient Gate-to-Emitter Voltage	$V_{GES}$	$\pm 20$ $\pm 30$	V	
Collector Current	$I_C$	$T_C = 25^\circ\text{C}$	150	A
		$T_C = 100^\circ\text{C}$	75	
Pulsed Collector Current (Note 1)	$I_{LM}$	300	A	
Pulsed Collector Maximum Current (Note 2)	$I_{CM}$	300	A	
Diode Forward Current	$I_F$	$T_C = 25^\circ\text{C}$	125	A
		$T_C = 100^\circ\text{C}$	75	
Pulsed Diode Maximum Forward Current (Note 2)	$I_{FM}$	300	A	
Maximum Power Dissipation	$P_D$	$T_C = 25^\circ\text{C}$	455	W
		$T_C = 100^\circ\text{C}$	227	
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +175	$^\circ\text{C}$	
Maximum Lead Temperature for Soldering Purposes (1/8" from case for 5 seconds)	$T_L$	300	$^\circ\text{C}$	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1.  $V_{CC} = 400\text{ V}$ ,  $V_{GE} = 15\text{ V}$ ,  $I_C = 300\text{ A}$ ,  $R_G = 73\ \Omega$ , Inductive Load
2. Repetitive rating: pulse width limited by max. Junction temperature

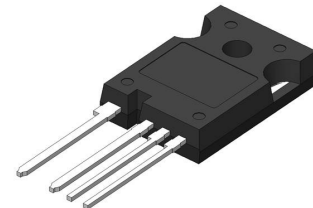
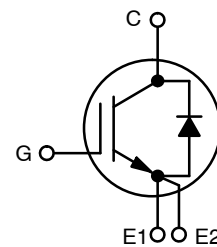
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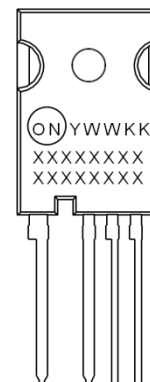
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**75 A, 650 V**  
 $V_{CE(\text{sat})} = 1.6\text{ V}$   
 $E_{\text{on}} = 1.06\text{ mJ}$



TO-247  
THIN LEADS  
CASE 340CW

#### DEVICE MARKING INFORMATION



Line 1: Date Code  
 Line 2: Device Marking  
 Line 3: Device Marking

#### ORDERING INFORMATION

Device	Package	Shipping
FGH75T65SHDTLN4	TO-247	30 Units / Tube

# FGH75T65SHDTLN4

**Table 1. THERMAL CHARACTERISTICS**

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, for IGBT	0.33	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case, for Diode	0.65	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	40	$^{\circ}\text{C}/\text{W}$

**Table 2. ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}\text{C}$  unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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**OFF CHARACTERISTICS**

Collector-emitter breakdown voltage, gate-emitter short-circuited	$BV_{CES}$	$V_{GE} = 0\text{ V}, I_C = 1\text{ mA}$	650	-	-	V
Temperature Coefficient of Breakdown Voltage	$\Delta BV_{CES}/\Delta T_J$	$V_{GE} = 0\text{ V}, I_C = 1\text{ mA}$	-	0.65	-	$\text{V}/^{\circ}\text{C}$
Collector-emitter cut-off current, gate-emitter short-circuited	$I_{CES}$	$V_{GE} = 0\text{ V}, V_{CE} = 650\text{ V}$	-	-	250	$\mu\text{A}$
Gate leakage current, collector-emitter short-circuited	$I_{GES}$	$V_{GE} = \pm 20\text{ V}, V_{CE} = 0\text{ V}$	-	-	$\pm 400$	nA

**ON CHARACTERISTICS**

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 75\text{ mA}$	4.0	5.5	7.5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15\text{ V}, I_C = 75\text{ A}, V_{GE} = 15\text{ V}, I_C = 75\text{ A}, T_J = 175^{\circ}\text{C}$	-	1.6 2.28	2.1 -	$\text{mV}/^{\circ}\text{C}$

**DYNAMIC CHARACTERISTICS**

Input Capacitance	$C_{ies}$	$V_{CE} = 30\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$	-	3710	-	pF
Output Capacitance	$C_{oes}$		-	183	-	
Reverse Transfer Capacitance	$C_{res}$		-	43	-	
Gate Charge Total	$Q_g$	$V_{CE} = 400\text{ V}, I_C = 75\text{ A}, V_{GE} = 15\text{ V}$	-	126	-	nC
Gate-to-Emitter Charge	$Q_{ge}$		-	24.1	-	
Gate-to-Collector Charge	$Q_{gc}$		-	47.6	-	

**SWITCHING CHARACTERISTICS, INDUCTIVE LOAD**

Turn-On Delay Time	$t_{d(on)}$	$T_C = 25^{\circ}\text{C}$ $V_{CC} = 400\text{ V}, I_C = 75\text{ A}$ $R_g = 15\ \Omega$ $V_{GE} = 15\text{ V}$ Inductive Load, $T_C = 25^{\circ}\text{C}$	-	55	-	ns	
Rise Time	$t_r$		-	50	-		
Turn-Off Delay Time	$t_{d(off)}$		-	189	-		
Fall Time	$t_f$		-	39	-		
Turn-On Switching Loss	$E_{on}$	$V_{CC} = 400\text{ V}, I_C = 75\text{ A}$ $R_g = 15\ \Omega$ $V_{GE} = 15\text{ V}$ Inductive Load, $T_C = 175^{\circ}\text{C}$	-	1.06	-	mJ	
Turn-Off Switching Loss	$E_{off}$		-	1.56	-		
Total Switching Loss	$E_{ts}$		-	2.62	-		
Turn-On Delay Time	$t_{d(on)}$		$V_{CC} = 400\text{ V}, I_C = 75\text{ A}$ $R_g = 15\ \Omega$ $V_{GE} = 15\text{ V}$ Inductive Load, $T_C = 175^{\circ}\text{C}$	-	48	-	ns
Rise Time	$t_r$			-	56	-	
Turn-Off Delay Time	$t_{d(off)}$			-	205	-	
Fall Time	$t_f$			-	40	-	
Turn-On Switching Loss	$E_{on}$	-		2.34	-	mJ	
Turn-Off Switching Loss	$E_{off}$	-		1.81	-		
Total Switching Loss	$E_{ts}$	-	4.15	-			

**DIODE CHARACTERISTICS**

Forward voltage	$V_F$	$I_F = 75\text{ A}$ $I_F = 75\text{ A}, T_J = 175^{\circ}\text{C}$	-	1.8 1.7	2.1 -	V
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# FGH75T65SHDTLN4

**Table 2. ELECTRICAL CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>DIODE CHARACTERISTICS</b>						
Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ\text{C}$ $I_F = 75\text{ A}, di_F/dt = 200\text{ A}/\mu\text{s}$	-	36	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	18	-	
Reverse Recovery Time	$t_{rr}$	$T_J = 175^\circ\text{C}$ $I_F = 75\text{ A}, di_F/dt = 200\text{ A}/\mu\text{s}$	-	270	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	2199	-	$\mu\text{C}$
Reverse Recovery Energy	$E_{rec}$		-	160	-	$\mu\text{J}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# FGH75T65SHDTLN4

## TYPICAL CHARACTERISTICS

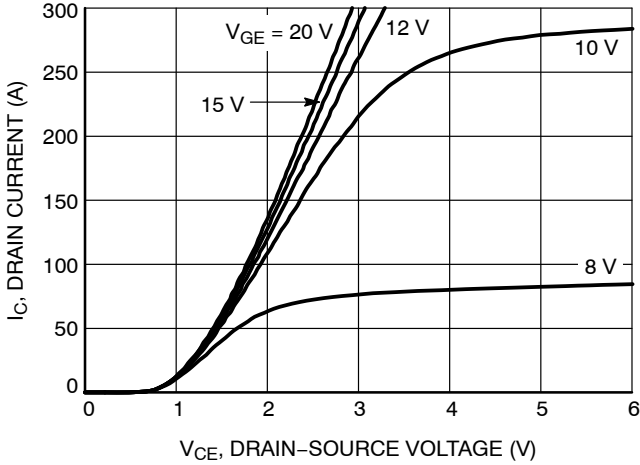


Figure 1. Typical Output Characteristics (25°C)

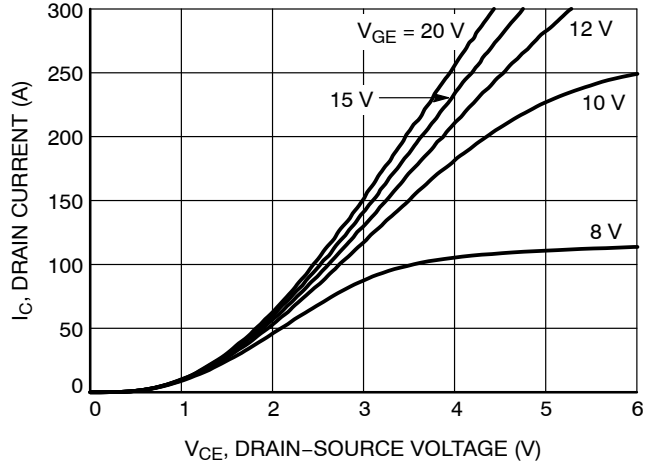


Figure 2. Typical Output Characteristics (175°C)

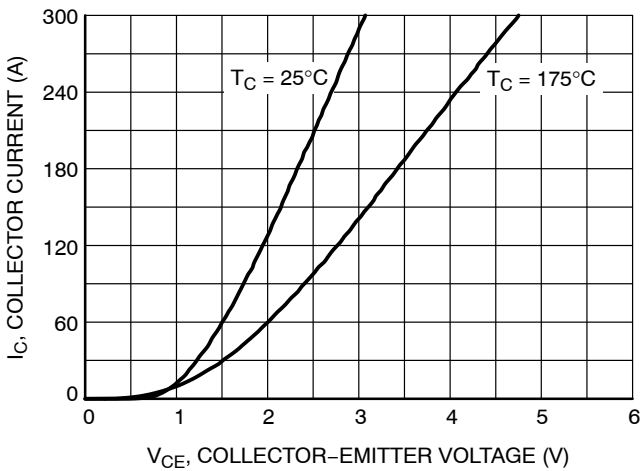


Figure 3. Typical Saturation Voltage Characteristics

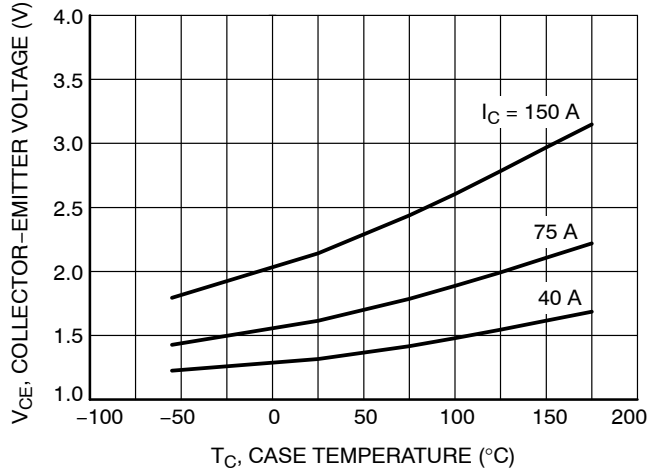


Figure 4. Saturation Voltage vs. Case Temperature at Variant Current Level

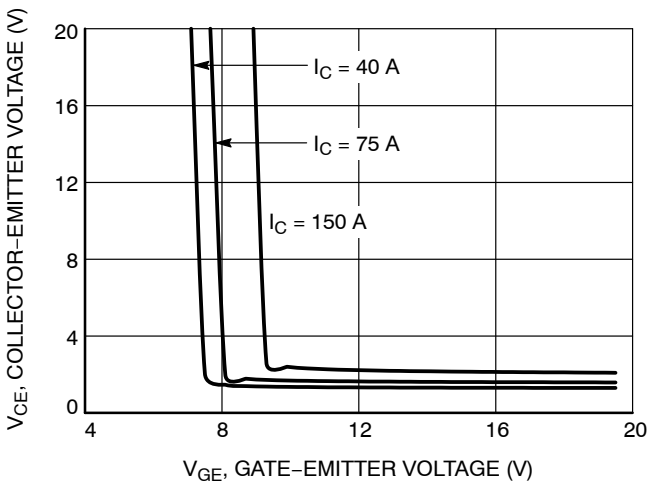


Figure 5. Saturation Voltage vs.  $V_{GE}$  (25°C)

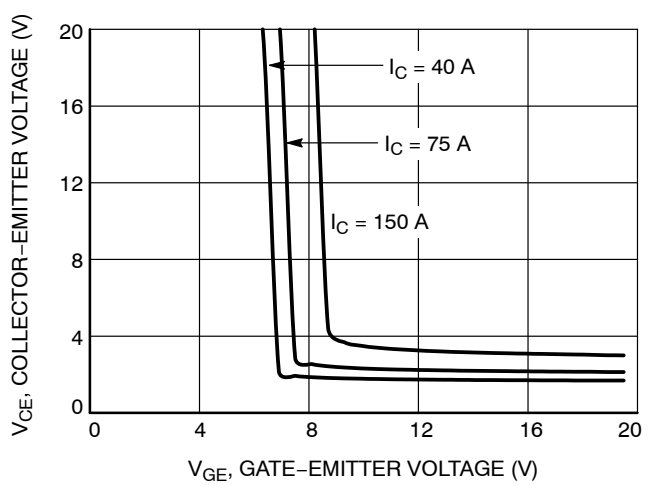


Figure 6. Saturation Voltage vs.  $V_{GE}$  (175°C)

# FGH75T65SHDTLN4

## TYPICAL CHARACTERISTICS

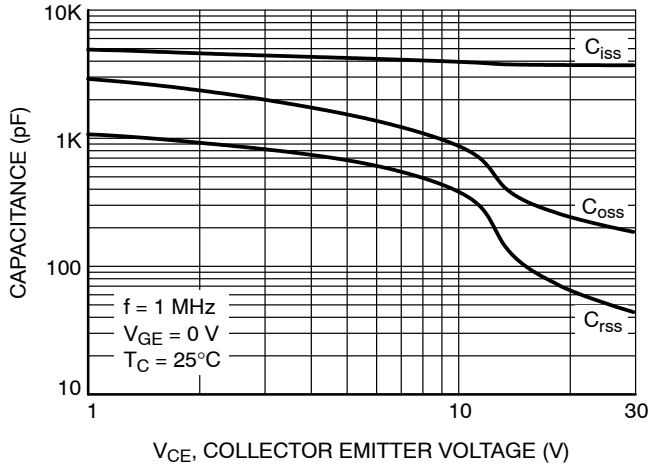


Figure 7. Capacitance Characteristics

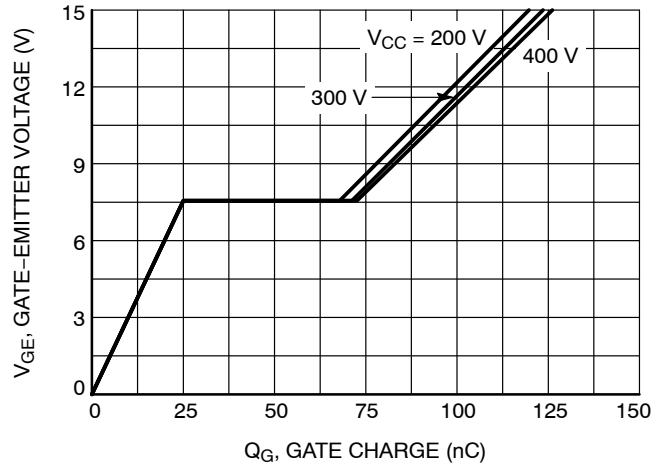


Figure 8. Gate Charge Characteristics

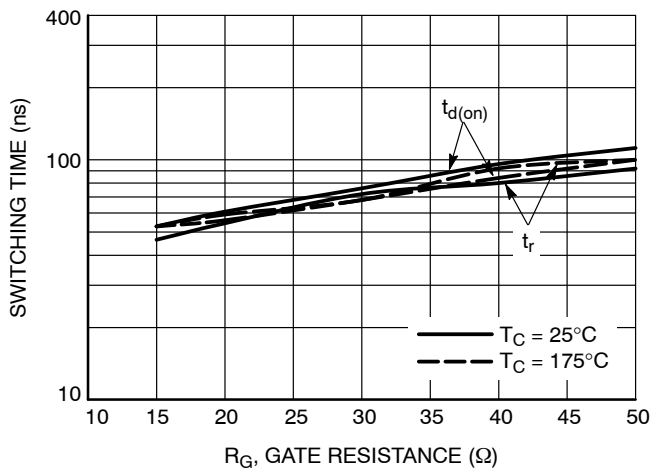


Figure 9. Turn-On Characteristics vs. Gate Resistance

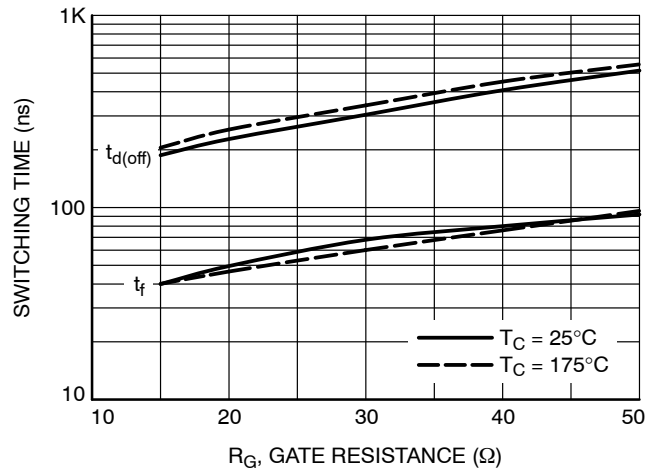


Figure 10. Turn-Off Characteristics vs. Gate Resistance

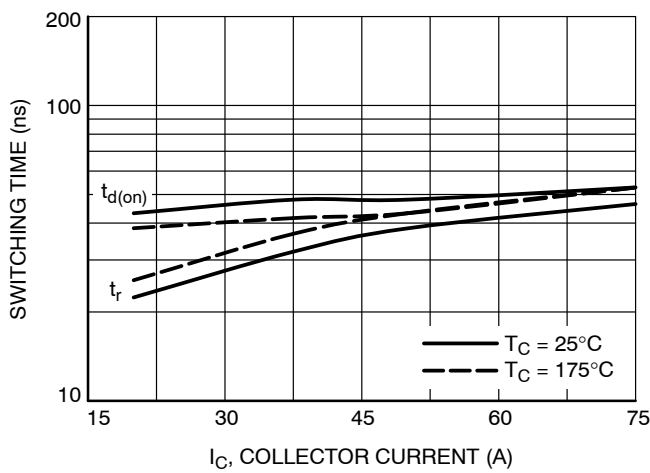


Figure 11. Turn-On Characteristics vs. Collector Current

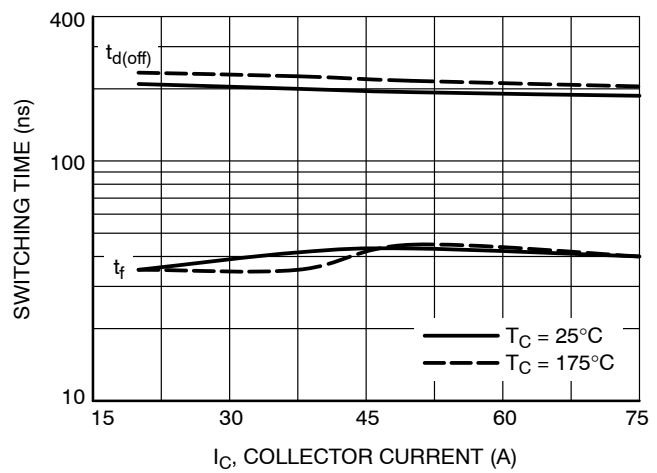


Figure 12. Turn-Off Characteristics vs. Collector Current

# FGH75T65SHDTLN4

## TYPICAL CHARACTERISTICS

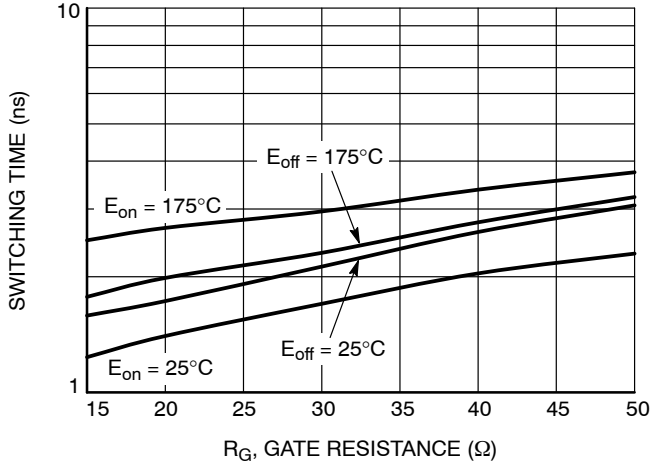


Figure 13. Switching Loss vs. Gate Resistance

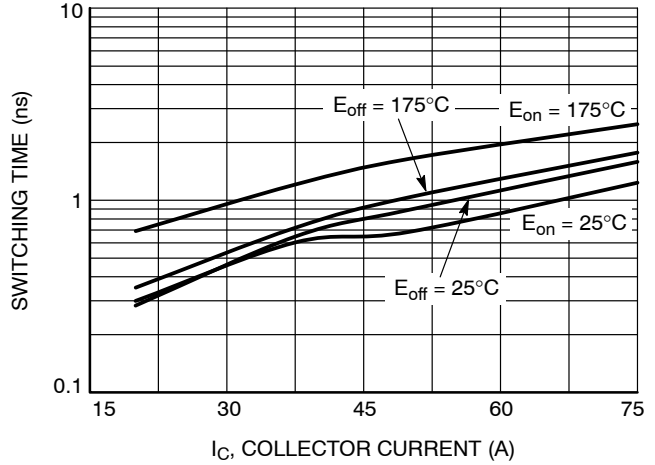


Figure 14. Switching Loss vs. Collector Current

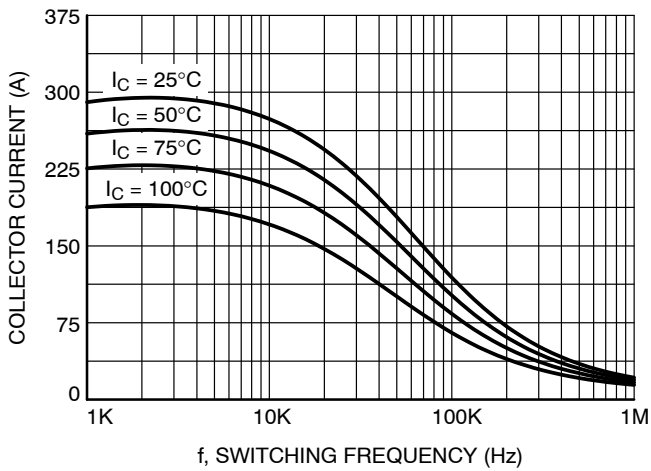


Figure 15. Load Frequency Template

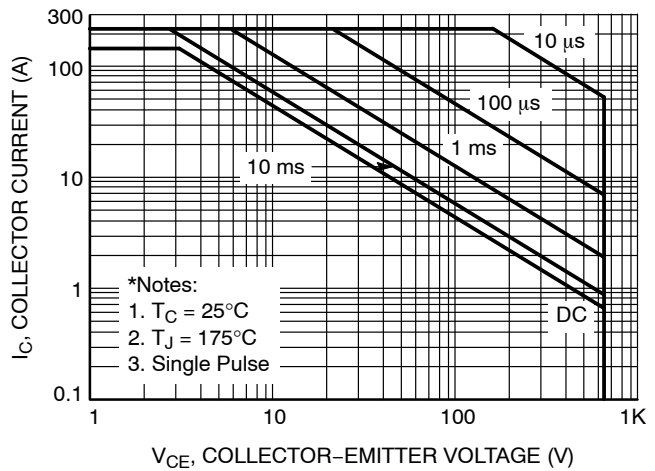


Figure 16. SOA Characteristics

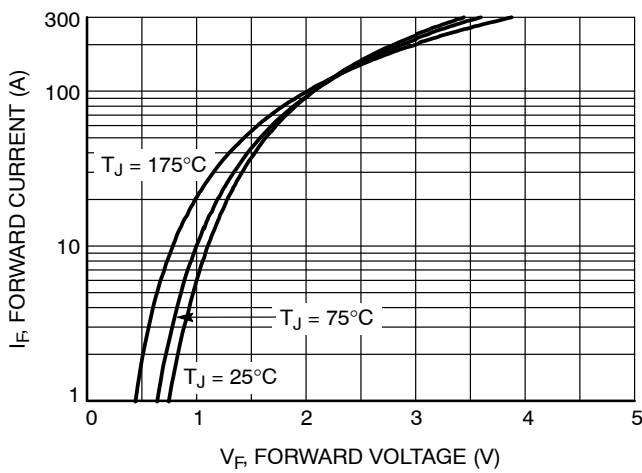


Figure 17. Forward Characteristics

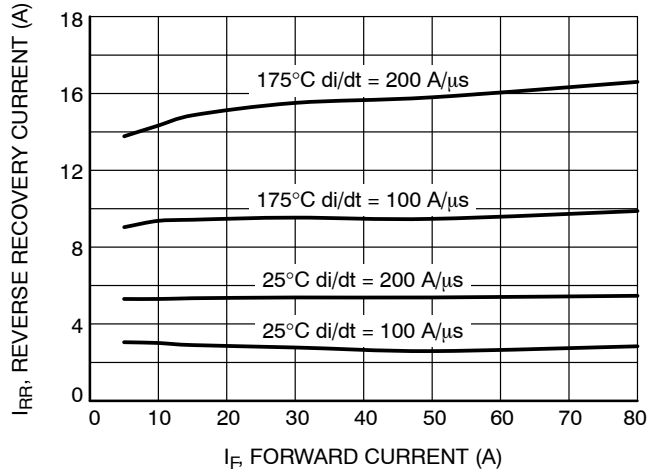


Figure 18. Reverse Recovery Current

# FGH75T65SHDTLN4

## TYPICAL CHARACTERISTICS

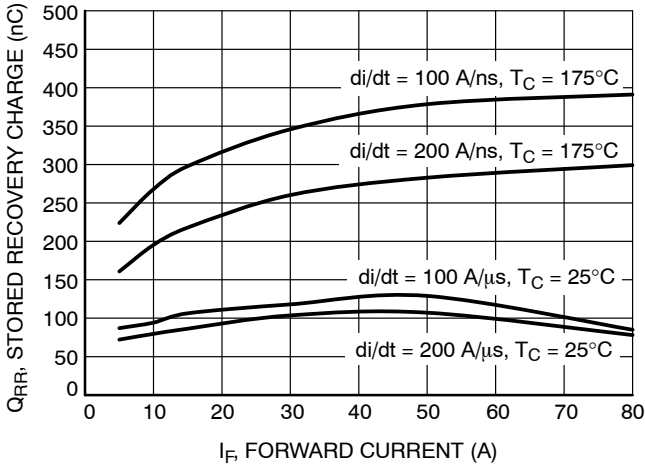


Figure 19. Reverse Recovery Time

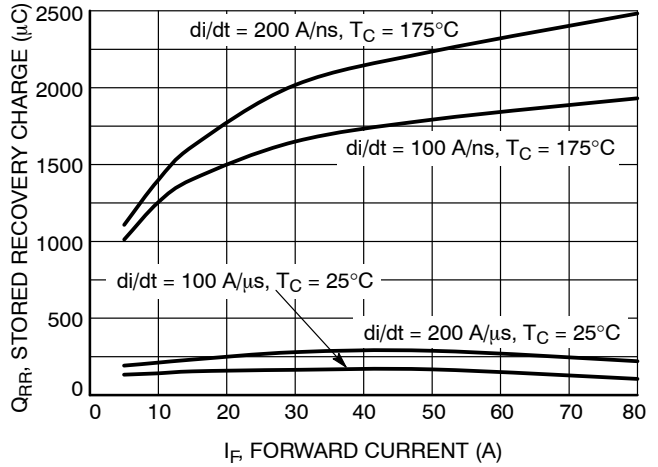


Figure 20. Stored Charge

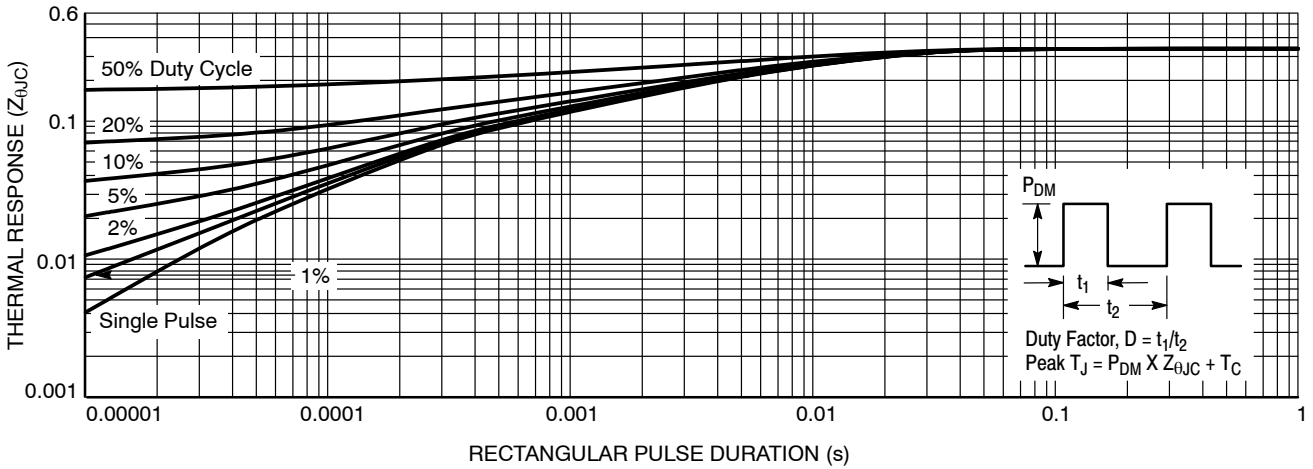


Figure 21. Transient Thermal Impedance of IGBT

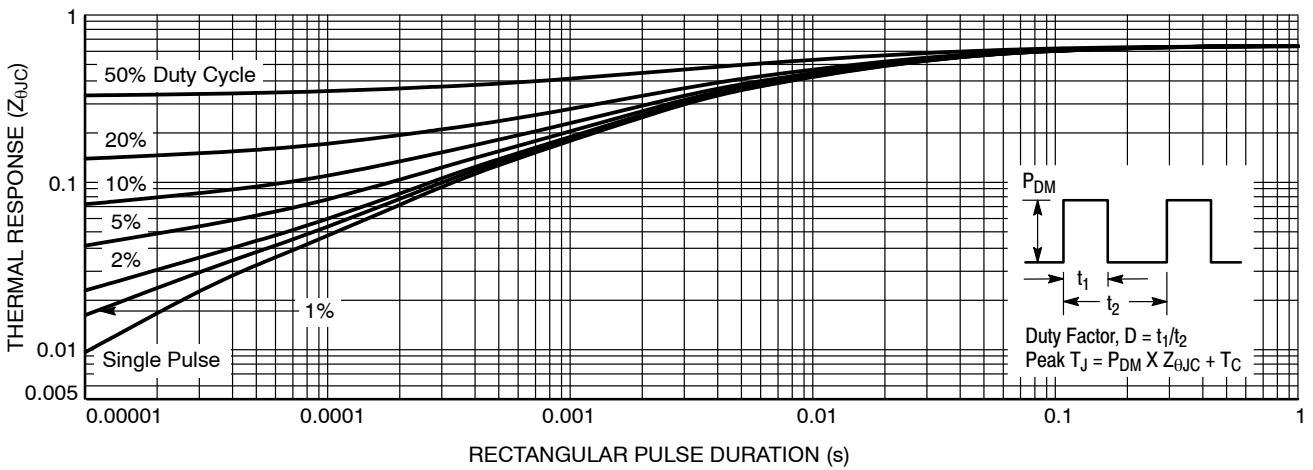
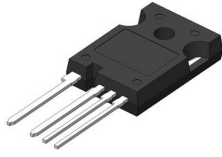


Figure 22. Transient Thermal Impedance of Diode

# MECHANICAL CASE OUTLINE

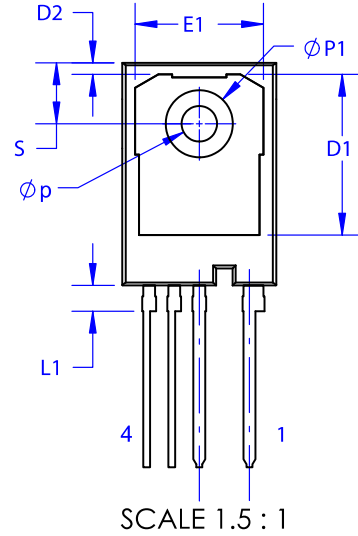
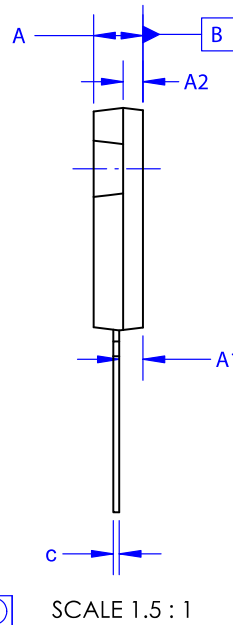
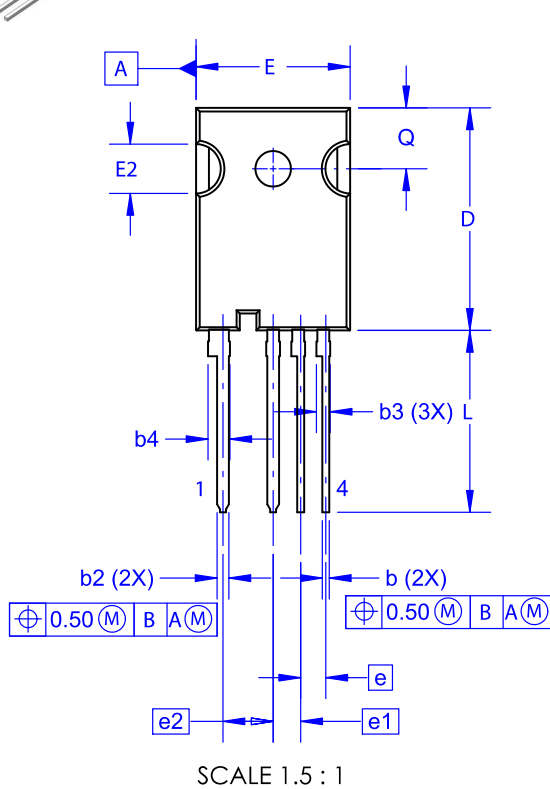
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### TO-247 4-LEAD, THIN LEADS CASE 340CW ISSUE A

DATE 16 SEP 2019



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- C. ALL DIMENSIONS ARE IN MILLIMETERS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.10	2.40	2.70
A2	1.80	2.00	2.20
b	0.57	0.70	0.83
b2	1.07	1.20	1.33
b3	1.20	1.40	1.60
b4	2.02	2.22	2.42
c	0.50	0.60	0.70
D	22.34	22.54	22.74
D1	16.00	16.30	16.50
D2	0.97	1.17	1.37
e		2.54	
e1		2.79	
e2		5.08	
E	15.40	15.60	15.80
E1	12.80	13.00	13.20
E2	4.80	5.00	5.20
L	18.12	18.42	18.72
L1	2.42	2.62	2.82
Øp	3.40	3.60	3.80
ØP1	6.60	6.80	7.00
Q	5.97	6.17	6.37
S	5.97	6.17	6.37

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